Market News

Infineon introduces HybridPACK™ Drive G2, a new automotive power module for traction inverter in electric vehicles

Munich, Germany – 28 April, 2023 – Infineon Technologies AG (FSE: IFX / OTCQX: IFNNY) today launched a new automotive power module: The HybridPACK™ Drive G2. It builds on the well-established HybridPACK Drive G1 concept of an integrated B6 package, offering scalability within the same footprint and extending it to higher power and ease-of-use. The HybridPACK Drive G2 will be available with different current ratings, voltage levels (750V and 1200V) and Infineon's next generation chip technologies EDT3 (Si IGBT) and CoolSiC™ G2 MOSFET.

With a power range of up to 300 kW within the 750 V and 1200 V classes, the HybridPACK Drive G2 provides high ease-of-use and new features, such as an integration option for next-generation phase current sensor and on-chip temperature sensing for IGBT products, which enable system cost improvements. The power module achieves higher performance and power density through improved assembly and interconnect technology. The adoption of new interconnect technology (chip sintering) and of new materials (new black plastic housing) enables higher temperature rating, resulting in higher performance and longer product life.

The first generation (G1) of HybridPACK Drive was introduced in 2017, using silicon EDT2 technology. It offers a power range of 100 kW to 180 kW in the 750 V class. In 2021, Infineon expanded its product family with the first generation of HybridPACK Drive Automotive CoolSiC MOSFETs, which allowed the inverter design to achieve higher power up to 250 kW within the 1200 V class, longer driving range, smaller battery size and optimized system size and cost. With a track record of nearly 3 million units sold in various global electric vehicle platforms, the HybridPACK Drive is now Infineon's market-leading power module.

Availabilty

The lead products (FS1150R08, FS01MR08, FS02MR12) of the new HybridPACK Drive G2 are in production and will be available starting May 2023, with additional

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product variants to follow in 2023 and 2024. More information is available at www.infineon.com/hybridpackdrive.
The product will be showcased at PCIM Europe 2023; evalkits and design-in support are available to enable fast and easy evaluation for our customers.

Infineon at the PCIM 2023

At the PCIM Europe 2023 tradeshow, Infineon is showcasing innovative product-to-system solutions for applications that will power the world and shape the future. Company representatives will also be giving several presentations at the accompanying PCIM Conference and Industry & E-Mobility Forum with live and on-demand video presentations, followed by discussions with the speakers. “Driving decarbonization and digitalization. Together.” at the Infineon booth #412 in hall 7, 9-11 May, 2023 in Nuremberg/Germany. Information about the PCIM Europe 2023 show highlights is available at www.infineon.com/pcim.

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